



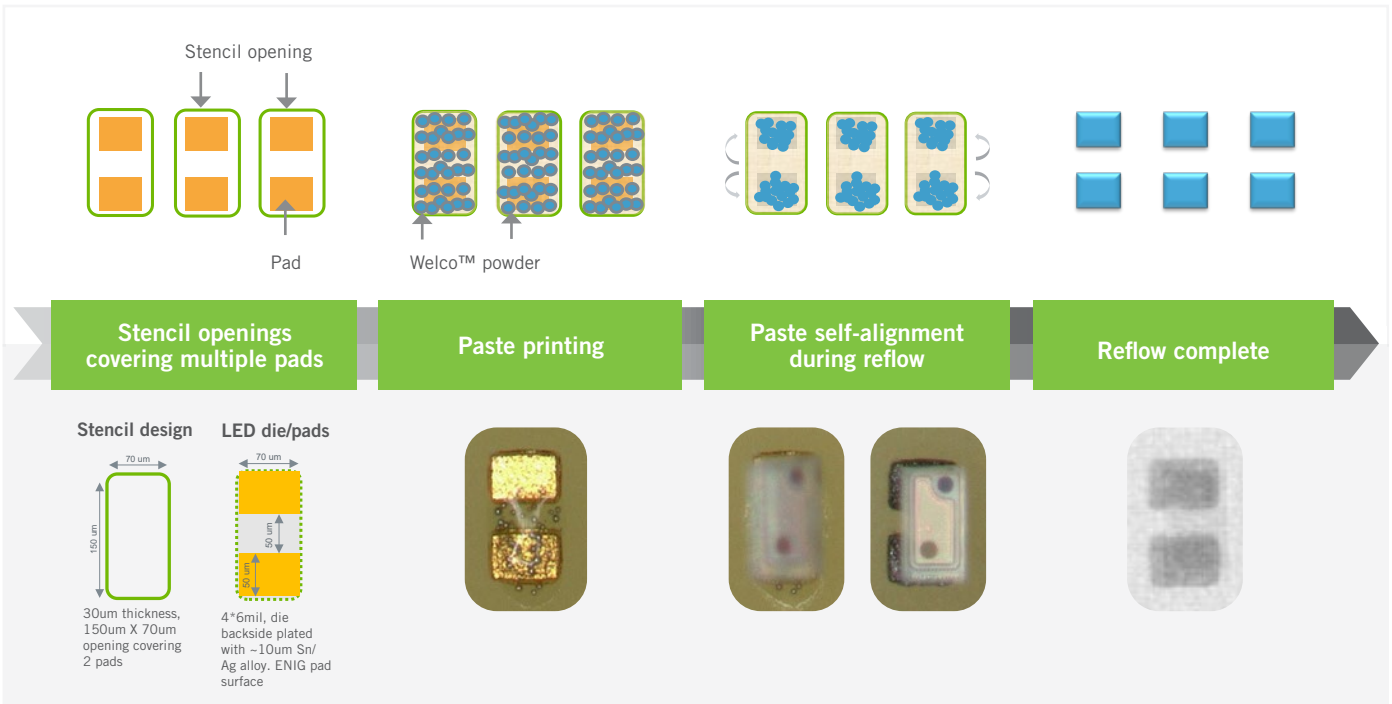
## Welco™ LED101 No-Clean SAC305 T6 Paste

Welco™ LED101 SAC305 T6 paste is a state-of-the-art no-clean printing paste engineered for mini-LED and micro-LED attach, or SiP applications. The paste is designed to be printed through stencil openings covering 2 or more substrate pads each and self-align to the pads after reflow without bridging. The LED101 solder paste also possesses high tackiness to facilitate the effective transfer of mini and micro-LED dies. The LED101 series uses only Heraeus Electronics proprietary Welco™ powders to achieve low voids and high yield solder joints for customers' ultra-fine pitch applications.

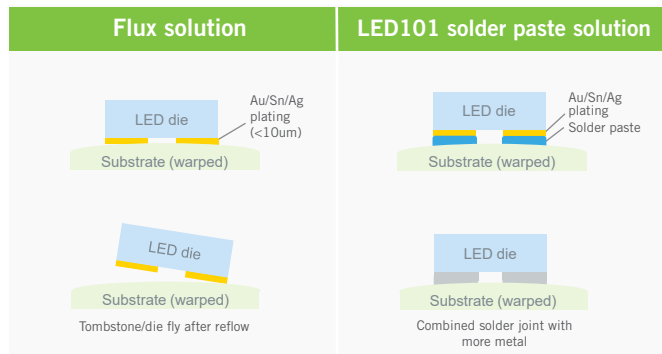
### Key features

- Uses high-quality Welco™ Type 6 powders
- No clean and halogen free chemistry
- Self-alignment during reflow
- Best-in-class low-voids performance
- Better solder joint reliability than using pure flux
- Long stencil life ( $\geq 8$ hr) & staging life ( $\geq 8$ hr)
- High tackiness for effective mini and micro-LED die transfer process

## Feature 1: Welco™ LED101 solder paste with self-alignment property

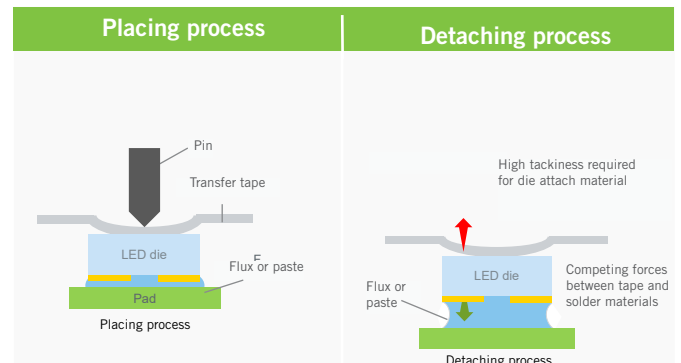


## Feature 2: Higher solder joint reliability



- As mini and micro-LED dies get smaller, there is insufficient solder to hold the dies if flux alone is used.
- Metal powders in paste help promote metal coalescence, pulling dies to the substrate and reducing cold joint.

## Feature 3: High tackiness for effective die transfer



- Welco™ LED101 provides high tackiness for effective die transfer.

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